

Article

# A Novel Seedless TSV Process based on Room Temperature Curing Silver Nanowires ECAs for MEMS Packaging

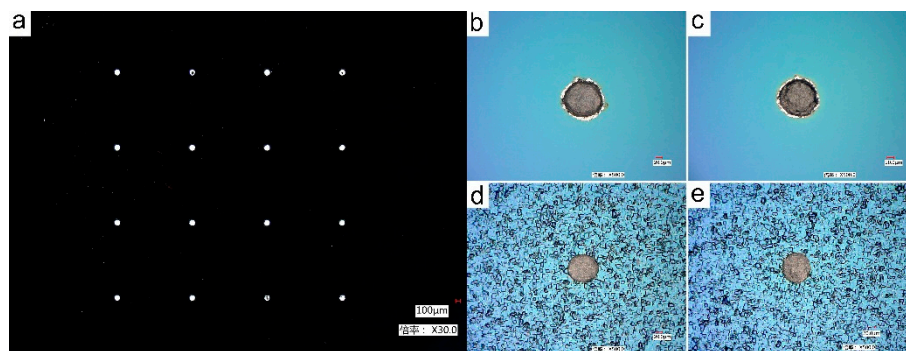
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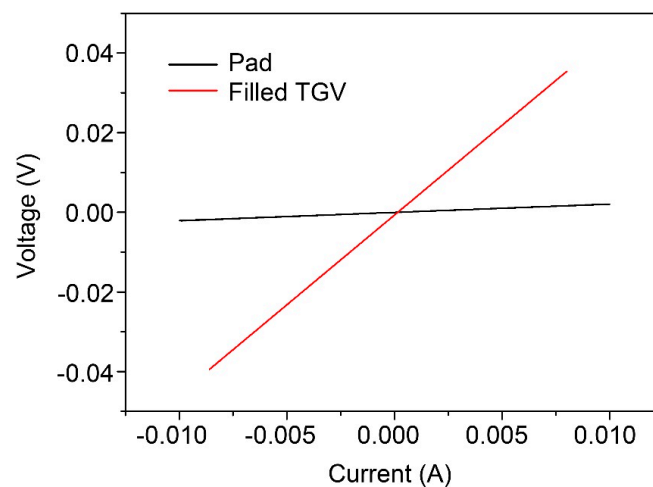
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**Figure S1.** (a) Low magnification optical image of the filled TSVs array with overburden layer being removed by a scraper. (b,c) Magnified optical images of the top side of a fully filled TSV randomly selected from (a). (d,e) Magnified optical images of the back side of a fully filled TSV randomly selected from (a).



**Figure S2.** I-V measurement curves of a fully filled TGV with 30 wt% silver nanowires ECAs (red) and deposited Ti/Au pad (black).